

Date: August 2026
Rev: XIV
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 1.22 Part B: 1.02
Pot Life: < 2 Hours
Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: Six months at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):

May not achieve performance properties listed below
 150°C / 1 Minute
 120°C / 5 Minutes
 100°C / 10 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**
- Black color is cosmetic only, and not intended to be photonic, spectral, or lampblack. All users need to confirm its opacity versus wavelength.

Product Description: EPO-TEK® 353ND Black is a two component, high temperature epoxy designed for semiconductor, hybrid, and fiber optic applications.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:				
* Color (before cure):	Part A: Black	Part B: Amber		
* Consistency:	Pourable liquid			
* Viscosity (23°C) @ 50 rpm:	3,000 - 5,000	cPs		
Thixotropic Index:	N/A			
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):				
	Below Tg:	54	x 10 ⁻⁶ in/in°C	
	Above Tg:	206	x 10 ⁻⁶ in/in°C	
Shore D Hardness:	85			
Lap Shear @ 23°C:	> 2,000	psi		
Die Shear @ 23°C:	≥ 15	Kg	5,334	psi
Degradation Temp:	420	°C		
Weight Loss:				
	@ 200°C:	0.92	%	
	@ 250°C:	1.24	%	
	@ 300°C:	1.83	%	
Suggested Operating Temperature:	< 325	°C (Intermittent)		
Storage Modulus:	516,912	psi		
Ion Content:	Cl ⁻ :	595 ppm	Na ⁺ :	52 ppm
	NH ₄ ⁺ :	1149 ppm	K ⁺ :	16 ppm
Particle Size:	N/A			
ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	N/A			
Volume Resistivity @ 23°C:	≥ 1.6 x 10 ¹³	Ohm-cm		
Dielectric Constant (1KHz):	3.09			
Dissipation Factor (1KHz):	0.005			
OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission:	< 3 % @ 1500	nm		
Refractive Index:	N/A			

Epoxyes and Adhesives for Demanding Applications™

SELLER MAKES NO OTHER WARRANTY OR GUARANTEE OF ANY KIND REGARDING FITNESS OF THE PRODUCT FOR A PARTICULAR PURPOSE. BUYER ASSUMES FULL RESPONSIBILITY FOR QUALITY CONTROL, TESTING AND DETERMINATION OF SUITABILITY OF PRODUCT FOR ITS INTENDED APPLICATION OR USE.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

www.epotek.com

EPO-TEK® 353ND Black Advantages & Suggested Application Notes:

- EPO-TEK® 353ND Black has been color-coded black for optical applications requiring opacity against light in IR and VIS region.
- Reasonable pot-life that allows for low temperature curing to be realized.
- Semiconductor suggested applications: wafer-wafer bonding of CSP, fabrication of MEMs devices, flip chip underfill.
- Hybrid suggested applications: providing near hermetic seals in sensor devices, resisting high temperature packaging.
- Fiber optic adhesive designed to meet Telecordia 1221 - suggested applications:
 - Sealing fiber into ferrules, transmitting light in the optical pathway from 800- 1550 nm range.
 - Fiber component packaging; adhesive for active alignment of optics, environmental seal of opto-package, V-groove arrays.
 - Down-Hole petrochemical fiber optic sensors, resisting >200 C field conditions
 - Passes MIL-STD-810E, Method 508.4 Fungus Resistance Testing
- Electronics Assembly suggested applications:
 - Used as dielectric layer in the fabrication of capacitors; laminating PZT ferroelectrics found in ultrasound or ink-jetting devices.
 - Impregnating and insulating copper coil windings in motors and inductor coils. Bonding ferrite cores and magnets.
 - Structural grade epoxy found in hard-disk drive devices; bonding of SST metals, kapton, and magnets.
- For an ISO 10993 biocompatible version, see EPO-TEK® MED-353ND BLACK.

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